



Material Content Data Sheet



Sales Product Name				IPD082N10N3 G		Issued		24. January 2018	
MA#				MA001662900					
Package				PG-TO252-3-313		Weight*		320.15 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.609	1.44	1.44	14397	14397	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	iron	7439-89-6	0.147	0.05		460		
	non noble metal	copper	7440-50-8	147.096	45.95	46.01	459466	460064	
	non noble metal	aluminium	7429-90-5	3.987	1.25	1.25	12452	12452	
wire	non noble metal	aluminium	7429-90-5	3.987	1.25	1.25	12452	12452	
encapsulation	organic material	carbon black	1333-86-4	1.361	0.43		4252		
	plastics	epoxy resin	-	23.822	7.44		74411		
	inorganic material	silicondioxide	60676-86-0	110.944	34.65	42.52	346542	425205	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11682	11682	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4437	4448	
solder	non noble metal	tin	7440-31-5	0.075	0.02		235		
	noble metal	silver	7440-22-4	0.094	0.03		294		
	non noble metal	lead	7439-92-1	3.600	1.12	1.17	11243	11772	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59902	59980	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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